

**Notice of References Cited**

Application/Control No.

09/938,644

Applicant(s)/Patent Under  
Reexamination  
RUEGER, NEAL

Examiner

Terrence Mackey

Art Unit

1765

Page 1 of 1

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
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**NON-PATENT DOCUMENTS**

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	U	Method of Increasing the Deposition and Etch Rates in Plasma Processes, IBM Technical Disclosure Bulletin, vol. 25, No. 7A, Dec. 1982, p. 3161.
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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
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